

Amendments to the Claims

1-13.(cancelled)

14.(previously presented) A semiconductor die package, comprising a semiconductor die and a permanent protective material surrounding substantially all of the die, the protective material fully curable by exposure to ultraviolet light and shrinking 10% or less by volume upon curing.

15.(previously presented) A semiconductor die package, comprising:
a semiconductor die;
conductive leads electrically connected to the die; and
protective material covering substantially all of the die and at least a portion of the leads, the protective material fully curable by exposure to ultraviolet light and shrinking 10% or less by volume upon curing.

16.(previously presented) The semiconductor die package of Claim 15, wherein the protective material is formed from a mixture including a polymer resin and a photoactive compound.

17.(previously presented) The semiconductor die package of Claim 16, wherein the polymer resin comprises a phenol-formaldehyde epoxy novolac resin and the photoactive compound comprises triaryl sulfonium hexafluorophosphate.

18.(previously presented) The semiconductor die package of Claim 17, wherein the protective material is formed from a mixture including about 44% by volume phenol-formaldehyde epoxy novolac resin and about 1% by volume triaryl sulfonium hexafluorophosphate.

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Response to Office Action

-2-

19.(currently amended) A method, comprising:
coating substantially all of a semiconductor die with a polymer that is fully
curable by exposure to ultraviolet light and shrinks 10% or less by volume upon curing;
and
fully curing the coating solely by exposing the coating to ultraviolet light.

20.(canceled)

21.(previously presented) A method, comprising:
coating substantially all of a semiconductor die with a mixture of a phenol-
formaldehyde epoxy novolac resin and triaryl sulfonium hexafluorophosphate; and
exposing the coating to ultraviolet light.

22.(previously presented) The method of Claim 21, wherein coating comprises
coating the semiconductor die with a mixture of about 44% by volume phenol-
formaldehyde epoxy novolac resin and about 1% by volume triaryl sulfonium
hexafluorophosphate.

23-25.(canceled)